COMPLIANT

HALOGEN FREE

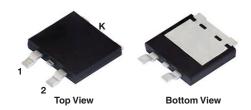


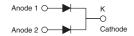
### Vishay General Semiconductor

# Dual High-Voltage TMBS® (Trench MOS Barrier Schottky) Rectifier

Ultra Low  $V_F = 0.58 \text{ V}$  at  $I_F = 2.5 \text{ A}$ 

### eSMP<sup>®</sup> Series SMPD (TO-263AC)





#### **DESIGN SUPPORT TOOLS AVAILABLE**



PRIMARY CHARACTERISTICS				
I <sub>F(AV)</sub>	2 x 5 A			
V <sub>RRM</sub>	150 V			
I <sub>FSM</sub>	80 A			
$V_F$ at $I_F = 5$ A $(T_A = 125  ^{\circ}\text{C})$	0.68 V			
T <sub>J</sub> max.	175 °C			
Package	SMPD (TO-263AC)			
Circuit configuration	Common cathode			

#### **FEATURES**

- Trench MOS Schottky technology
- Very low profile typical height of 1.7 mm
- · Ideal for automated placement
- · Low forward voltage drop, low power losses
- · High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available:
  - Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912"><u>www.vishav.com/doc?99912</u></a>

#### TYPICAL APPLICATIONS

For use in high frequency DC/DC converters, switching power supplies, freewheeling diodes, OR-ing diode, and reverse battery protection in commercial, industrial, and automotive application.

### **MECHANICAL DATA**

Case: SMPD (TO-263AC)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and

AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per

J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

Polarity: as marked

MAXIMUM RATINGS (T <sub>A</sub> = 25 °C unless otherwise noted)					
PARAMETER		SYMBOL	V10DM150C	UNIT	
Device marking code			V10DM150C		
Maximum repetitive peak reverse voltage		V <sub>RRM</sub>	150	V	
Maximum average forward rectified current (fig. 1)	per device	I <sub>F(AV)</sub> <sup>(1)</sup>	10	Α	
	per diode		5	A 	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load		I <sub>FSM</sub>	80	А	
Operating junction temperature range		T <sub>J</sub> <sup>(2)</sup>	-40 to +175	- °C	
Storage temperature range		T <sub>STG</sub>	-55 to +175		

#### Notes

<sup>(1)</sup> Mounted on infinite heatsink

 $<sup>^{(2)}</sup>$  The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta,JA}$ 



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<b>ELECTRICAL CHARACTERISTICS</b> (T <sub>A</sub> = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage per diode	I <sub>F</sub> = 2.5 A	- T <sub>A</sub> = 25 °C	V <sub>F</sub> (1)	0.77	-	V
	I <sub>F</sub> = 5 A			1.05	1.15	
	I <sub>F</sub> = 2.5 A	T <sub>A</sub> = 125 °C		0.58	-	
	I <sub>F</sub> = 5 A			0.68	0.76	
Reverse current at rated V <sub>R</sub> per diode	V <sub>R</sub> = 100 V	T <sub>A</sub> = 25 °C	I <sub>R</sub> <sup>(2)</sup>	0.01	-	mA
		T <sub>A</sub> = 125 °C		1	-	
	V <sub>R</sub> = 150 V	T <sub>A</sub> = 25 °C		-	0.1	
	v <sub>R</sub> = 150 v	T <sub>A</sub> = 125 °C		2	4	
Typical junction capacitance	4.0 V, 1 MHz		CJ	300	-	pF

#### Notes

 $^{(1)}$  Pulse test: 300  $\mu$ s pulse width, 1 % duty cycle

(2) Pulse test: Pulse width  $\leq 5 \text{ ms}$ 

THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)				
PARAMETER	ARAMETER SYMBOL V10DM150C		UNIT	
Typical thermal resistance per device	R <sub>0</sub> JC <sup>(1)</sup>	2.7	°C/W	
	R <sub>0JA</sub> (1)(3)	58	C/VV	

#### Notes

- (1) Mounted on infinite heatsink
- $^{(2)} \ \ The \ heat \ generated \ must \ be \ less \ than \ the \ thermal \ conductivity \ from \ junction-to-ambient: \ dP_D/dT_J < 1/R_{\theta JA} \ \ junction-to-ambient \ dP_D/dT_J < 1/R_{\theta JA} \ \ junct$
- (3) Free air, without heatsink

ORDERING INFORMATION (Example)					
PREFERRED P/N	UNIT WEIGHT (g)	PACKAGE CODE	BASE QUANTITY	DELIVERY MODE	
V10DM150C-M3/I	0.55	1	2000/reel	13" diameter plastic tape and reel	
V10DM150CHM3/I (1)	0.55	1	2000/reel	13" diameter plastic tape and reel	

#### Note

(1) AEC-Q101 qualified



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### **RATINGS AND CHARACTERISTICS CURVES** (T<sub>A</sub> = 25 °C unless otherwise noted)

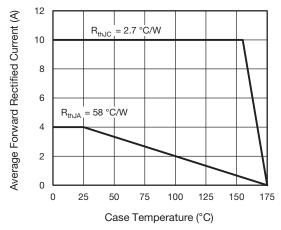


Fig. 1 - Maximum Forward Current Derating Curve

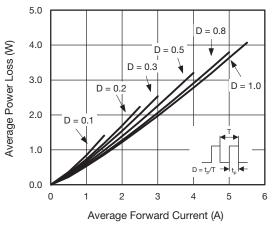


Fig. 2 - Average Power Loss Characteristics

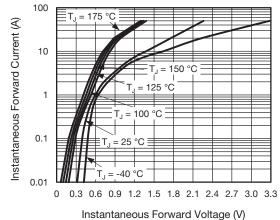


Fig. 3 - Typical Instantaneous Forward Characteristics

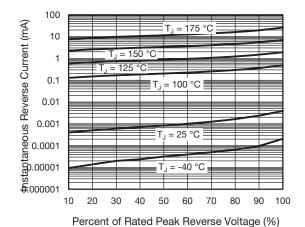


Fig. 4 - Typical Reverse Leakage Characteristics

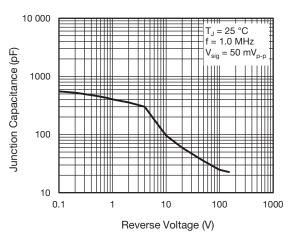


Fig. 5 - Typical Junction Capacitance

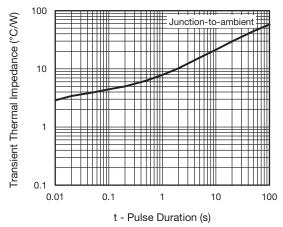


Fig. 6 - Typical Transient Thermal Impedance



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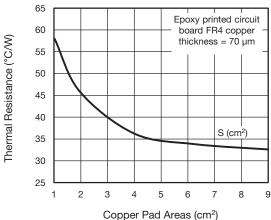


Fig. 7 - Thermal Resistance Junction-to-Ambient vs. Copper Pad Areas

### PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

### SMPD (TO-263AC) 0.071 (1.80) 0.063 (1.60) 0.386 (9.80) 0.020 (0.52) 0.011 (0.27) 0.059 (1.50) REF. 0.048 (1.21) 0.032 (0.81) 0.354 (8.99) 0.338 (8.59) 0.509 (12.93) 0.485 (12.33) 0 to 0.01 (0 to 0.254) 0.069 (1.74) 0.053 (1.34) 0.063 (1.60) 0.020 (0.52) 0.011 (0.27) 0.047 (1.20) 0.200 (5.08) NOM: 0.052 (1.23) 0.028 (0.72) Mounting Pad Layout 0.420 (10.66) MIN. 0.339 (8.60) 0.323 (8.20) 0.276 (7.00) 0.260 (6.60) 0.330 (8.38) REF. 0.194 (4.93) NOM 0.604 (15.33) 0.525 (13.33) 0.120 (3.05) REF. 0.105 (2.67) 0.080 (2.03) MIN.



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